

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Takahisa NAKASHIMA	12/02/2005
Makoto TAKEMURA	12/02/2005
Yasuyuki HASHIMOTO	12/02/2005
RECEIVING PARTY DATA	
Name:	SUMCO CORPORATION
Street Address:	2-1, Shibaura 1-chome, Minato-ku
City:	Tokyo
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12575728
CORRESPONDENCE DATA	
Fax Number:	(703)770-7901
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	7037707900
Email:	shylah.dobson@pillsburylaw.com
Correspondent Name:	PILLSBURY WINTHROP SHAW PITTMAN, LLP
Address Line 1:	P.O. BOX 10500
Address Line 4:	MCLEAN, VIRGINIA 22102
ATTORNEY DOCKET NUMBER:	061063-0382583
NAME OF SUBMITTER:	Shylah L. Dobson
Total Attachments: 1 source=061063382583ASSIGNMENT#page1.tif	

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Please return signed/recorded to:

Pillsbury Winthrop LLP
Intellectual Property Group
P.O. Box 10500
McLean, VA 22102

USA Patent Appln.
Sole or Joint

For Inventions made outside USA
executed with or after application
Atty. Dkt. P0324246 | OSP-19260
M# | Client Ref.

NONPROVISIONAL

ASSIGNMENT
OF NONPROVISIONAL APPLICATION

NONPROVISIONAL

In consideration of the sum of Ten Dollars (\$10.00) and other good and valuable consideration paid to each of the undersigned, to wit:

INSERT
NAME(S) OF
INVENTOR(S)

(1) Takahisa NAKASHIMA	(2) Makoto TAKEMURA
(3) Yasuyuki HASHIMOTO	(4)
(5)	<input type="checkbox"/> x box if continued on page 2

the receipt and sufficiency of which are hereby acknowledged by the undersigned who at the request of, hereby sell(s), assign(s) and transfer(s) unto:

INSERT
NAME(S) OF
ASSIGNEE(S)
& ADDRESS(ES)

SUMCO CORPORATION of 2-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan

(hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all applications including any and all divisions, continuations, substitutes, and reissues thereof; and all resulting patents, known as

TITLE OF
INVENTION

ALKALI ETCHING LIQUID FOR SILICON WAFER AND ETCHING METHOD USING SAME

for which the undersigned executed an application for Letters Patents of the United States of America:

NOTE → →

(Complete

line A, B and/or C)

(A) even date herewith

(B) on

(C) in U.S. Appln. No. / filed

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorney of record in said application shall hereinafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

NOTE → → The undersigned hereby authorize(s) Pillsbury Winthrop LLP of the above address to insert hereon any further identification necessary or desirable for recordation of this document.

INVENTORS	DATE SIGNED	WITNESSES
1): <u>Takahisa NAKASHIMA</u> Name: Takahisa NAKASHIMA	Dec. 2, 2005	<u>Tamohira Horie</u>
2): <u>Makoto Takemura</u> Name: Makoto TAKEMURA	Dec. 2, 2005	<u>Tamohira Horie</u>
3): <u>Yasuyuki Hashimoto</u> Name: Yasuyuki HASHIMOTO	Dec. 2, 2005	<u>Tamohira Horie</u>
4) Name: _____	_____	_____
Name: _____	_____	_____
5) Name: _____	_____	_____
Name: _____	_____	_____